

# S606

## Thermal Compound



### Features

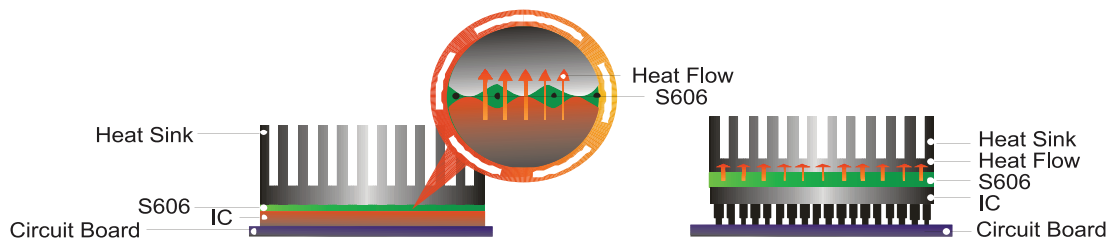
Good thermal conductivity  
Easy to assemble  
High stability  
Does not harden with time

### Applications

Electronic components: IC / CPU / MOS  
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /  
Wireless Hub etc....  
DDR II Module / DVD Applications / Hand-Set applications etc...

### Storage

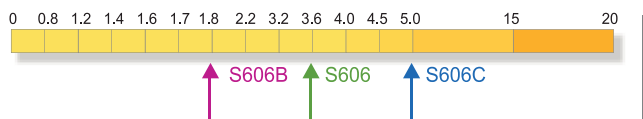
S606 has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened container at, or below 25 °C.



### Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: (W / m.k - Z Axis)



S606B Thermal Conductivity 1.8 W/m.k  
S606 Thermal Conductivity 3.6 W/m.k  
S606C Thermal Conductivity 5.0 W/m.k

| Property             | S606              | S606B             | S606C             | Unit              | Test Method |
|----------------------|-------------------|-------------------|-------------------|-------------------|-------------|
| Colour               | White             | White             | Grey              | -                 | Visual      |
| Thermal Conductivity | 3.6               | 1.8               | 5                 | W/m.k             | ASTM D5470  |
| Weight Loss          | <0.5              | <0.5              | <0.5              | %                 | ASTM E595   |
| Specific Gravity     | 2.3               | 2.3               | 2.3               | g/cm <sup>3</sup> | ASTM D792   |
| Working Temperature  | -40~+180          | -40~+180          | -40~+180          | °C                | -           |
| Volume Resistance    | >10 <sup>12</sup> | >10 <sup>12</sup> | >10 <sup>12</sup> | Ohm-cm            | ASTM D257   |
| Standard Package     | 30                | 30                | 30                | g/pot             | -           |

S606(C) - 30 gram  
1. Part Number  
2. Quantity